

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Dror Hurwitz</td> <td>03/18/2013</td> </tr> <tr> <td>Simon Chan</td> <td>03/18/2013</td> </tr> <tr> <td>Alex Huang</td> <td>03/18/2013</td> </tr> </tbody> </table>		Name	Execution Date	Dror Hurwitz	03/18/2013	Simon Chan	03/18/2013	Alex Huang	03/18/2013
Name	Execution Date								
Dror Hurwitz	03/18/2013								
Simon Chan	03/18/2013								
Alex Huang	03/18/2013								
RECEIVING PARTY DATA									
Name:	Zhuhai Advanced Chip Carriers & Electronic Substrate Solutions Technologies Co. Ltd.								
Street Address:	FounderPCB Industry Park								
Internal Address:	Fushan Industry Zone								
City:	Qianwu, Doumen, Zhuhai								
State/Country:	CHINA								
Postal Code:	519173								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13713550</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13713550				
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Application Number:	13713550								
CORRESPONDENCE DATA									
Fax Number:	2037822889								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	203-498-4566								
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Correspondent Name:	Gregory S. Rosenblatt								
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ATTORNEY DOCKET NUMBER:	103589-100								
NAME OF SUBMITTER:	Gregory S. Rosenblatt								
Signature:	/Gregory S Rosenblatt/								

PATENT

Date:

04/24/2013

Total Attachments: 2

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ASSIGNMENT

WHEREAS, we

Dror HURWITZ, residing at RM 3105, Building 1, no. 227, Shuiwan Road, Gongbei, Zhuhai, Guangdong Province, People's Republic of China,

Simon CHAN, residing at Access Founder PCB Industry Park, Fushan Industry Zone, Qianwu Town, Doumen District, Zhuhai, P.R. China. 519173

and

Alex HUANG, residing at Access Founder PCB Industry Park, Fushan Industry Zone, Qianwu Town, Doumen District, Zhuhai, P.R. China. 519173

have invented certain new and useful improvements in

SINGLE LAYER CORELESS SUBSTRATE

for which

(X) we filed an application for Letters Patent of the United States on 13 DECEMBER 2012 under U.S. Application No. 13/713550; and

WHEREAS, **Zhuhai Advanced Chip Carriers & Electronic Substrate Solutions Technologies Co. Ltd., FounderPCB Industry Park, Fushan Industry Zone, Qianwu, Doumen, Zhuhai, P.R. China. 519173** ("Assignee"), organized under the laws of **P.R. China**, is desirous of obtaining the entire right, title and interest in, to and under the said improvements and the said application;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said Assignee, its successors, legal representatives, and assigns the entire right, title and interest in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States and all extensions, renewals, and reissues thereof; and we hereby authorize and request the Commissioner for Patents of the United States and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on application as aforesaid, to issue all Letters Patent for said improvement to the said Assignee, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

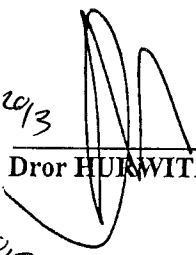
AND WE HEREBY covenant that WE have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

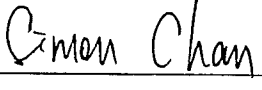
AND WE HEREBY further covenant and agree that we will communicate to said Assignee, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, continuation-in-part and reissue applications, make all rightful oaths, and generally do everything possible to aid the said Assignee, its successors, legal representatives and assigns to obtain and enforce proper patent protection for said improvements in all countries.

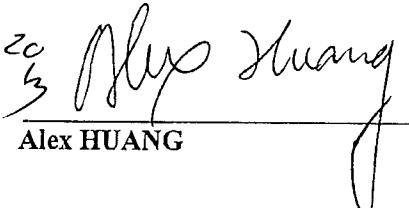
AND WE HEREBY further assign and transfer to Assignee all priority rights derived from such application therefore by virtue of the International Convention for the Protection of Industrial Property for any and all member countries of the aforesaid International Convention, and we do hereby assign and transfer to Assignee the sole right to file further applications for patents under the patent laws of any country of the world based on any improvements disclosed in said application as fully and entirely as the same would have been held by me had this assignment not been made.

AND Assignee HEREBY assumes all right, title and interest in and to this application and the improvements disclosed therein, any Letters Patents or reissues or reexamined patents that may be granted upon said application, to the end of the term or terms for which such Letters Patent are or may be granted or reissued or reexamined.

IN TESTIMONY WHEREOF, we hereunto set our hands and seals the day and year set opposite our signatures.

Date: 18th day of Mar. 2013 
Dror HUKWITZ

Date: 18th day of Mar 2013 
Simon CHAN

Date: 18th day of Mar 2013 
Alex HUANG